

30V P-Channel Enhancement Mode MOSFET

Description

The PECN3007DR uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications.

General Features

- ◆ $V_{DS} = -30V$, $I_D = -7A$
 $R_{DS(ON)}(\text{Typ.}) = 36m\Omega$ @ $V_{GS} = -4.5V$
 $R_{DS(ON)}(\text{Typ.}) = 28m\Omega$ @ $V_{GS} = -10V$
- ◆ High power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

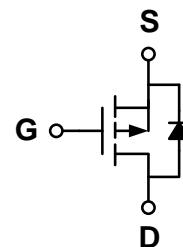
Application

- ◆ PWM applications
- ◆ Load switch

Package

100% UIS TESTED!

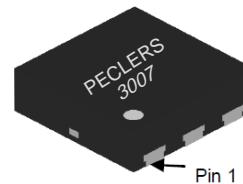
100% ΔV_{ds} TESTED!

Schematic diagram**Marking and pin assignment**

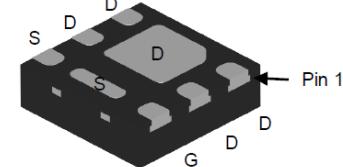
DFN2*2-6L-B

(Thickness 0.55mm)

Top View



Bottom View

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN3007DR	-55°C to +150°C	DFN2*2-6L-B	4000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	-30	V
Gate-source voltage	V_{GS}	± 20	V
Drain current-continuous ^a @Tj=125°C -pulse d ^b	I_D	-7	A
	I_{DM}	-28	A
Drain-source Diode forward current	I_S	-7	A
Maximum power dissipation	P_D	18	W
Operating junction Temperature range	Tj	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-30	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V	-	-	-1	μA
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.8	-1.3	-2	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-7A	-	28	35	mΩ
		V _{GS} =-4.5V, I _D =-5A	-	36	45	
Forward transconductance	g _f	V _{GS} =-5V, I _D =-7A	-	5	-	S
Dynamic Characteristics						
Input capacitance	C _{ISS}	V _{DS} =-15V, V _{GS} =0V f=1.0MHz	-	760	-	pF
Output capacitance	C _{OSS}		-	140	-	
Reverse transfer capacitance	C _{RSS}		-	95	-	
Switching Characteristics						
Turn-on delay time	t _{D(ON)}	V _{DS} =-15V V _{GS} =-10V R _L =2.3Ω R _{GEN} =3Ω	-	8	-	ns
Rise time	tr		-	6	-	
Turn-off delay time	t _{D(OFF)}		-	17	-	
Fall time	tf		-	5	-	
Total gate charge	Q _g	V _{DS} =-15V, I _D =-6A V _{GS} =-10V	-	13.6	-	nC
Gate-source charge	Q _{gs}		-	2.5	-	
Gate-drain charge	Q _{gd}		-	3.2	-	
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode forward voltage	V _{SD}	V _{GS} =0V, I _s =-1.25A	-	-0.81	-1.2	V

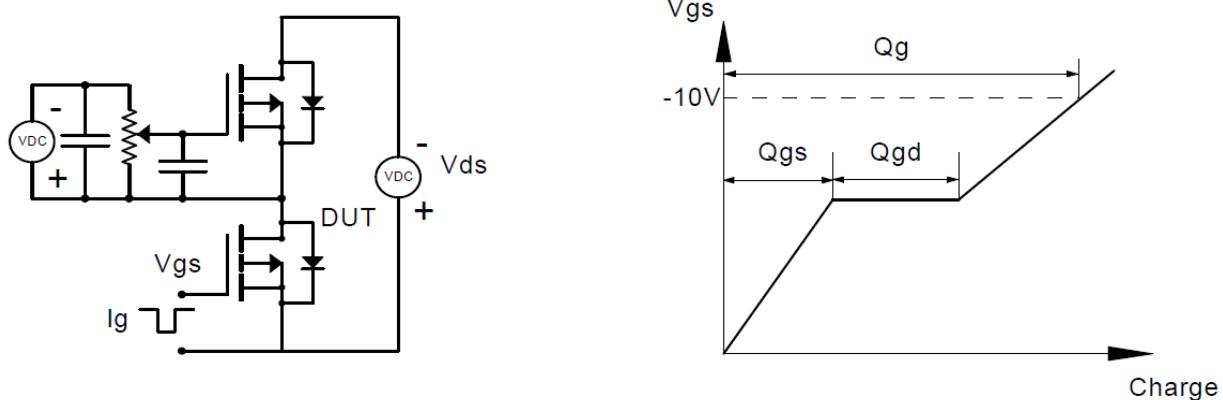
Notes:

- a. surface mounted on FR4 board, t≤10sec
- b. pulse test: pulse width≤300μs, duty≤2%
- c. guaranteed by design, not subject to production testing

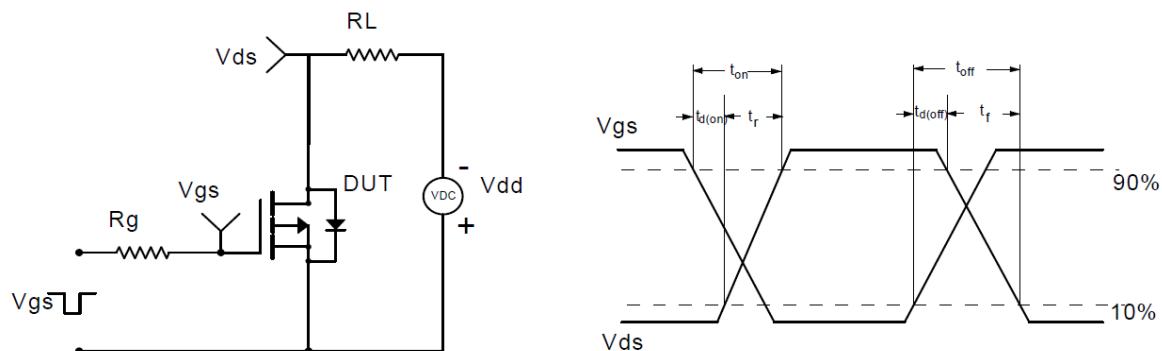
Thermal Characteristics

Thermal Resistance junction-to ambient	R _{th JA}	100	°C/W
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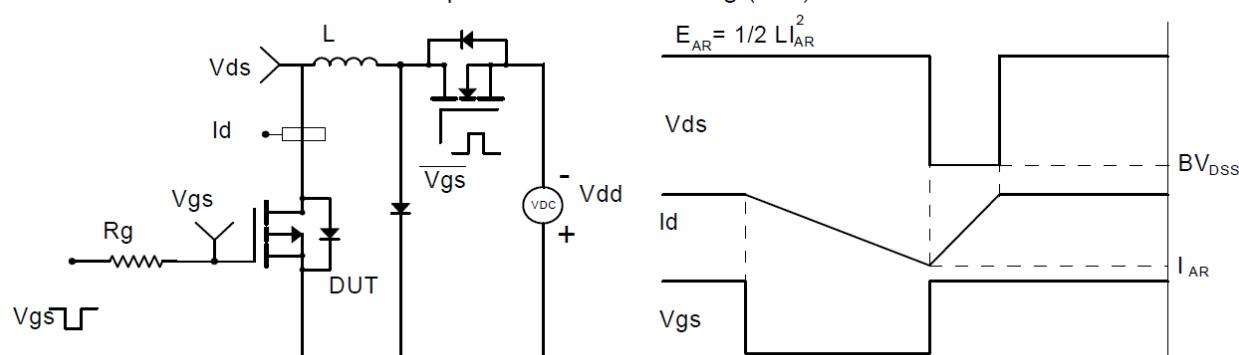
Gate Charge Test Circuit & Waveform



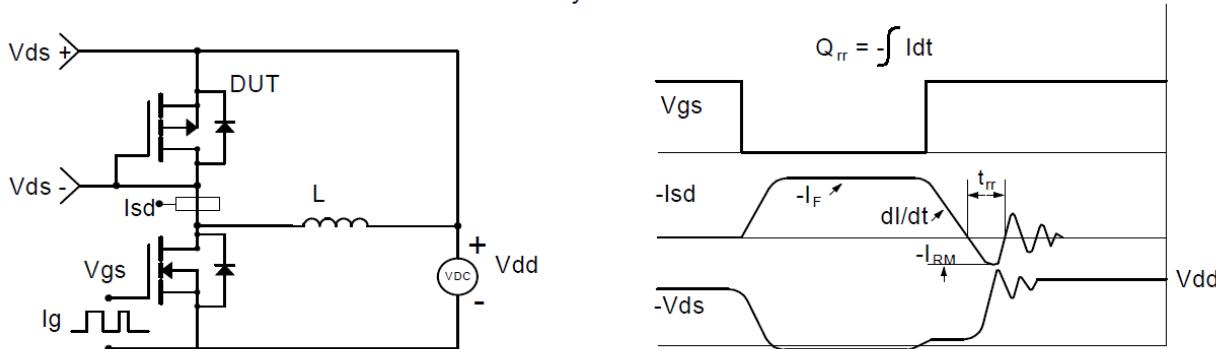
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

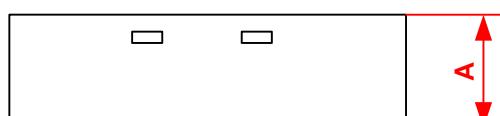


Package Information

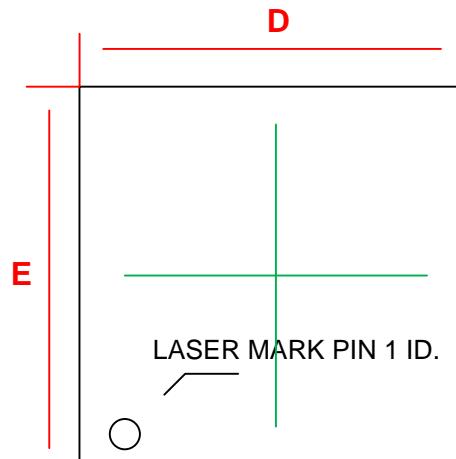
- DFN2*2-6L-B



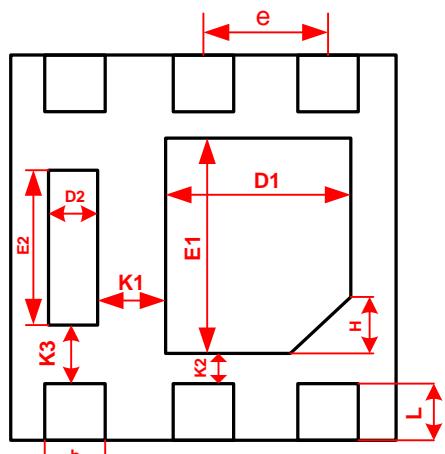
SIDE VIEW



SIDE VIEW



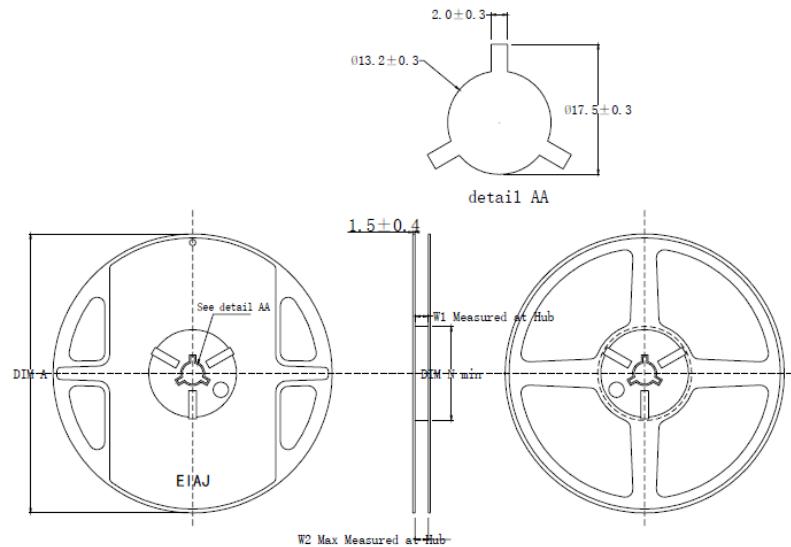
TOP VIEW



BOTTOM VIEW

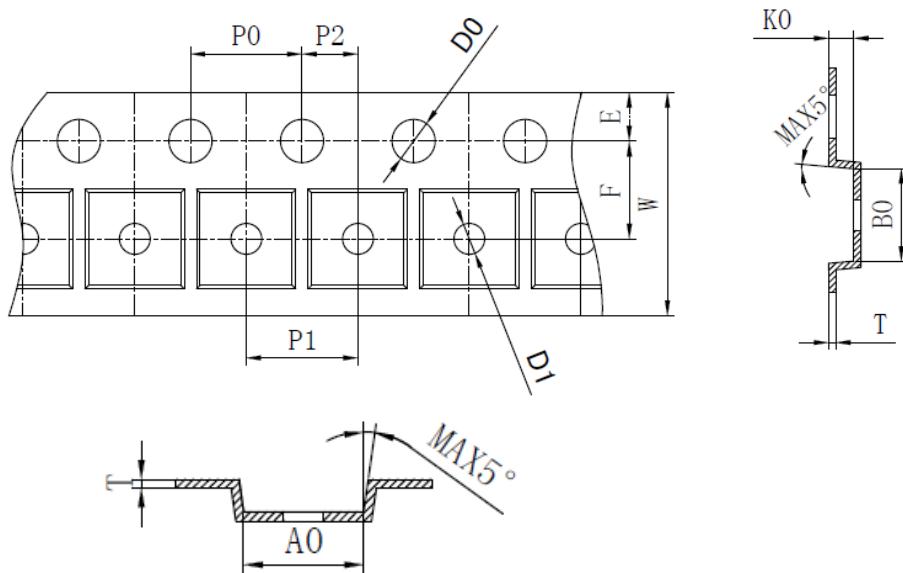
PKG	Common Dimension (mm)		
	DFN2020-6L-B		
SYMBOL	MIN.	MON.	MAX.
A	0.527	0.552	0.577
A2		0.127REF	
b	0.25	0.30	0.35
D	1.90	2.00	2.10
E	1.90	2.00	2.10
D1	0.85	0.95	1.05
E1	1.05	1.15	1.25
D2	0.20	0.25	0.30
E2	0.69	0.79	0.89
e	0.55	0.65	0.75
H	0.25	0.30	0.35
K1	0.25MIN		
K2	0.15MIN		
K3	0.20MIN		
L	0.20	0.25	0.30

Tape and Reel



PRODUCT SPECIFICATIONS

TYPE WIDTH	ϕA	ϕN	W1 (Min)	W2 (Max)
8MM	178 ± 2.0	60 ± 1.0	8.4	11.4
12MM	178 ± 2.0	60 ± 1.0	12.4	15.4



SYMBOL	A0	B0	K0	P0	P1	P2
SPEC	2.20 ± 0.05	2.20 ± 0.05	0.75 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05
SYMBOL	T	E	F	D0	D1	W
SPEC	0.20 ± 0.03	1.75 ± 0.10	3.50 ± 0.05	1.55 ± 0.05	$1.00^{+0.10}_{-0}$	$8.00^{+0.20}_{-0.10}$